



MSB12M

#### 1.2A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

### Product Summary (@TA = +25°C)

V <sub>RRM</sub> (V)	I <sub>O</sub> (A)	V <sub>F</sub> (V)	I <sub>R</sub> (μA)
1,000	1.2	1.1	5

### **Features and Benefits**

- Glass Passivated Die Construction
- Compact, Thin Profile Package Design
- Reliable Robust Construction
- Ideal for SMT Manufacturing
- Lead Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

## **Description and Applications**

Suitable for AC to DC bridge full-wave rectification for SMPS; LED lighting, adapters, battery chargers, home appliances, office equipment, and telecommunications applications.

### **Mechanical Data**

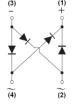
- Case: MSB
- Case Material: Molded Plastic; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe;
   Solderable per MIL-STD-202, Method 208 (@3)
- Polarity: As Marked on Body
- Weight: 0.09 grams (Approximate)

#### **MSB**



Top View





Internal Schematic

## **Ordering Information** (Note 4)

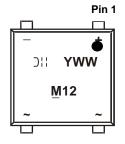
Part Number	Case	Packaging
MSB12M-13	MSB	3,000/Tape & Reel

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

### **Marking Information**

#### MSB



MXX = Product Type Marking Code,
(XX = 12)

II = Manufacturers' Code Marking
YWW = Date Code Marking
Y = Last Digit of Year (ex: 6 = 2016)
WW = Week Code (01 ~ 53)



## **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load. For capacitance load, derate current by 20%.

Characteristic		Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage		V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	1,000	٧
RMS Reverse Voltage		V <sub>R(RMS)</sub>	700	V
Average Rectified Output Current	@T <sub>C</sub> = +120°C	lo	1.2	Α
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load		I <sub>FSM</sub>	45	Α

# **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Typical Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	70	°C/W
Typical Thermal Resistance, Junction to Case	R <sub>θJC</sub>	10	°C/W
Typical Thermal Resistance, Junction to Lead	R <sub>0JL</sub>	30	°C/W
Operating and Storage Temperature Range	$T_{J,}T_{STG}$	-55 to +150	°C

# **Electrical Characteristics** (@ $T_A = +25^{\circ}C$ , unless otherwise specified.)

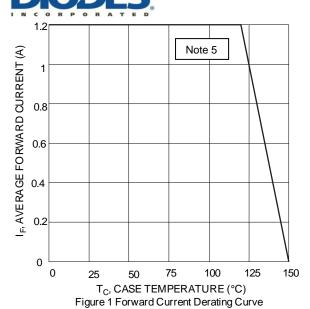
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	$V_{(BR)R}$	1,000	-		٧	$I_R = 5\mu A$
Forward Voltage	V <sub>F</sub>	_	0.9	1.1		I <sub>F</sub> = 0.6A
Torward Voltage	٧F	1	1.0	1.2		I <sub>F</sub> = 1.2A
Leakage Current (Note 6)	I <sub>R</sub>	_	_	5	μΑ	$V_R = 1,000V, T_A = +25$ °C $V_R = 1,000V, T_A = +125$ °C
Leakage Current (Note o)		1	1	500		$V_R = 1,000V, T_A = +125$ °C
Typical Total Capacitance	C <sub>T</sub>	1	30	1	pF	$V_R = 4V$ , $f = 1.0MHz$

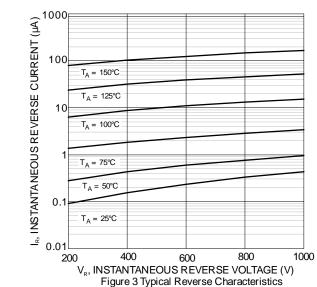
Notes:

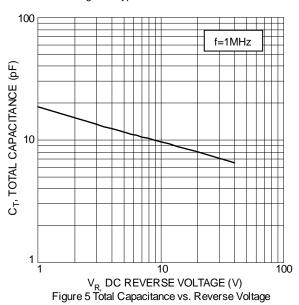
<sup>5.</sup> Device mounted on glass-epoxy substrate with 1 oz 20mm x 20mm Cu pad per pin.

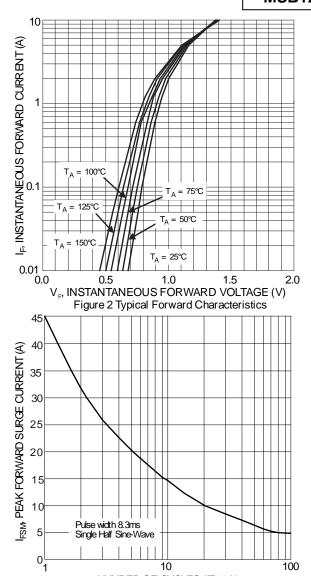
<sup>6.</sup> Short duration pulse test used to minimize self-heating effect.









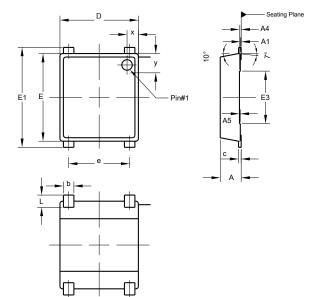


NUMBER OF CYCLES AT 60 H  $_{\rm Z}$  Figure 4 Forward Surge Current Derating Curve



# **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

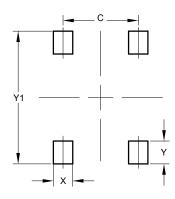


MSB					
Dim	Min	Max	Тур		
Α	1.10	1.30	1.20		
A1	0.00	0.05	0.02		
A4	0.05	0.08	-		
A5	0.03	0.08	0.05		
b	0.55	0.70	0.60		
С	0.12	0.18	0.15		
D	4.40	4.60	4.50		
E	4.90	5.10	5.00		
E1	5.60	5.80	5.70		
E3	2.95	3.05	3.00		
е	3.45	3.55	3.50		
L	0.65	0.75	0.70		
X	0.60	0.70	0.65		
у	0.60	0.70	0.65		
All Dimensions in mm					

# Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### **MSB**



Dimensions	Value (in mm)		
С	3.55		
Х	0.90		
Y	1.05		
Y1	6.10		



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